

# 74AUP1G17

Low-power Schmitt trigger

Rev. 9 — 4 November 2016

Product data sheet

## 1. General description

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The 74AUP1G17 provides the single Schmitt trigger buffer. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

This device ensures a very low static and dynamic power consumption across the entire  $V_{CC}$  range from 0.8 V to 3.6 V.

This device is fully specified for partial Power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

The inputs switch at different points for positive and negative-going signals. The difference between the positive voltage  $V_{T+}$  and the negative voltage  $V_{T-}$  is defined as the input hysteresis voltage  $V_H$ .

## 2. Features and benefits

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- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- ESD protection:
  - ◆ HBM JESD22-A114F Class 3A exceeds 5000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption;  $I_{CC} = 0.9 \mu\text{A}$  (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot  $< 10\%$  of  $V_{CC}$
- $I_{OFF}$  circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from  $-40\text{ }^\circ\text{C}$  to  $+85\text{ }^\circ\text{C}$  and  $-40\text{ }^\circ\text{C}$  to  $+125\text{ }^\circ\text{C}$



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AUP1G17GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74AUP1G17GV	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74AUP1G17GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AUP1G17GF	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74AUP1G17GN	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AUP1G17GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AUP1G17GX	-40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74AUP1G17GW	pJ
74AUP1G17GV	pJ
74AUP1G17GM	pJ
74AUP1G17GF	pJ
74AUP1G17GN	pJ
74AUP1G17GS	pJ
74AUP1G17GX	pJ

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

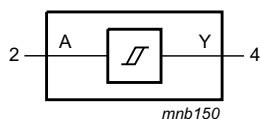


Fig 1. Logic symbol

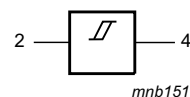


Fig 2. IEC logic symbol

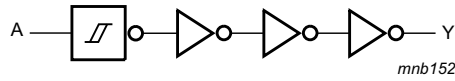


Fig 3. Logic diagram

## 6. Pinning information

### 6.1 Pinning

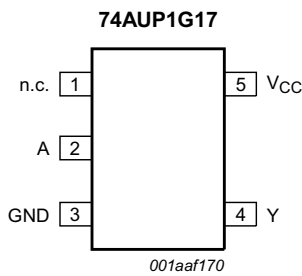


Fig 4. Pin configuration SOT353-1 and SOT753

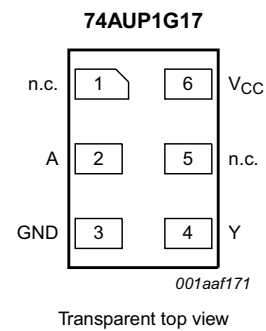


Fig 5. Pin configuration SOT886

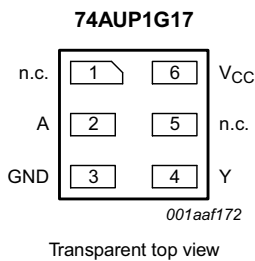


Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

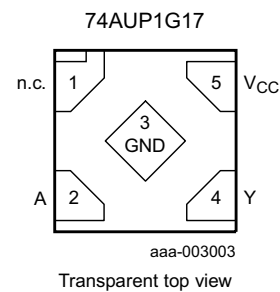


Fig 7. Pin configuration SOT1226 (X2SON5)

### 6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5, SC-74A and X2SON5	XSON6	
n.c.	1	1	not connected
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input	Output
A	Y
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+4.6	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		-0.5	+4.6	V
$I_{OK}$	output clamping current	$V_O < 0$ V	-50	-	mA
$V_O$	output voltage	Active mode and Power-down mode	-0.5	+4.6	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 20$	mA
$I_{CC}$	supply current		-	+50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
For XSON6 and X2SON5 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		0.8	3.6	V
$V_I$	input voltage		0	3.6	V
$V_O$	output voltage	Active mode	0	$V_{CC}$	V
		Power-down mode; $V_{CC} = 0$ V	0	3.6	V
$T_{amb}$	ambient temperature		-40	+125	°C

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = 25 °C</b>						
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.75 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.11	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.32	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	2.05	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.9	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.72	-	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.1	μA
		I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.5	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	-	-	40	μA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 0 V to 3.6 V	-	1.1	-	pF
C <sub>O</sub>	output capacitance	V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.7	-	pF
<b>T<sub>amb</sub> = -40 °C to +85 °C</b>						
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.1	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.7 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	1.03	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.30	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.97	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.85	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.67	-	-	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.1	μA
		I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.5	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	-	-	40	μA
C <sub>I</sub>	input capacitance	V <sub>I</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 0 V to 3.6 V	-	1.1	-	pF
C <sub>O</sub>	output capacitance	V <sub>O</sub> = GND; V <sub>CC</sub> = 0 V	-	1.7	-	pF

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.3 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.45	V		
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.5	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V to 0.2 V	-	-	±0.6	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.9	μA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 3.3 V	-	-	50	μA
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	V <sub>CC</sub> - 0.11	-	-	V
		I <sub>O</sub> = -1.1 mA; V <sub>CC</sub> = 1.1 V	0.6 × V <sub>CC</sub>	-	-	V
		I <sub>O</sub> = -1.7 mA; V <sub>CC</sub> = 1.4 V	0.93	-	-	V
		I <sub>O</sub> = -1.9 mA; V <sub>CC</sub> = 1.65 V	1.17	-	-	V
		I <sub>O</sub> = -2.3 mA; V <sub>CC</sub> = 2.3 V	1.77	-	-	V
		I <sub>O</sub> = -3.1 mA; V <sub>CC</sub> = 2.3 V	1.67	-	-	V
		I <sub>O</sub> = -2.7 mA; V <sub>CC</sub> = 3.0 V	2.40	-	-	V
I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.30	-	-	V		
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T-</sub>				
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	0.33 × V <sub>CC</sub>	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.50	V		
I <sub>I</sub>	input leakage current	V <sub>I</sub> = GND to 3.6 V; V <sub>CC</sub> = 0 V to 3.6 V	-	-	±0.75	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±0.75	μA

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta I_{OFF}$	additional power-off leakage current	$V_I$ or $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 0.2 V	-	-	$\pm 0.75$	$\mu$ A
$I_{CC}$	supply current	$V_I = GND$ or $V_{CC}$ ; $I_O = 0$ A; $V_{CC} = 0.8$ V to 3.6 V	-	-	1.4	$\mu$ A
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 3.3$ V	-	-	75	$\mu$ A

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max (85 °C)	Max (125 °C)	
<b><math>C_L = 5</math> pF</b>									
$t_{pd}$	propagation delay	A to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	19.0	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	2.6	5.7	10.6	2.5	10.9	11.1	ns
		$V_{CC} = 1.4$ V to 1.6 V	2.4	4.2	6.5	2.3	7.1	7.4	ns
		$V_{CC} = 1.65$ V to 1.95 V	2.0	3.6	5.5	1.9	6.1	6.3	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.9	3.0	4.2	1.8	4.6	4.8	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.8	2.7	3.6	1.5	3.8	4.0	ns
<b><math>C_L = 10</math> pF</b>									
$t_{pd}$	propagation delay	A to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	22.5	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	2.9	6.6	12.4	2.7	12.9	13.0	ns
		$V_{CC} = 1.4$ V to 1.6 V	2.6	4.8	7.8	2.4	8.3	8.7	ns
		$V_{CC} = 1.65$ V to 1.95 V	2.5	4.2	6.3	2.4	6.8	7.1	ns
		$V_{CC} = 2.3$ V to 2.7 V	2.3	3.5	4.8	2.1	5.3	5.6	ns
		$V_{CC} = 3.0$ V to 3.6 V	2.1	3.3	4.4	2.0	4.6	4.8	ns
<b><math>C_L = 15</math> pF</b>									
$t_{pd}$	propagation delay	A to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		$V_{CC} = 0.8$ V	-	26.0	-	-	-	-	ns
		$V_{CC} = 1.1$ V to 1.3 V	3.2	7.4	14.1	3.1	14.7	14.9	ns
		$V_{CC} = 1.4$ V to 1.6 V	3.1	5.4	8.7	2.8	9.5	9.9	ns
		$V_{CC} = 1.65$ V to 1.95 V	2.7	4.7	7.1	2.7	7.8	8.2	ns
		$V_{CC} = 2.3$ V to 2.7 V	2.6	4.0	5.6	2.5	6.0	6.3	ns
		$V_{CC} = 3.0$ V to 3.6 V	2.5	3.7	4.9	2.2	5.2	5.5	ns

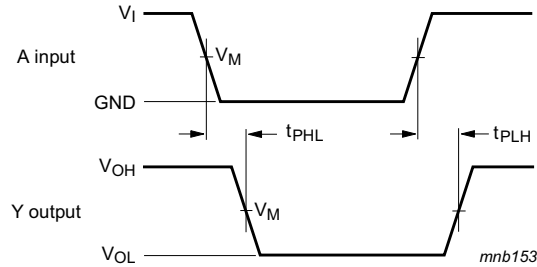
**Table 8. Dynamic characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#)

Symbol	Parameter	Conditions	25 °C			−40 °C to +125 °C			Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max (85 °C)	Max (125 °C)	
<b>C<sub>L</sub> = 30 pF</b>									
t <sub>pd</sub>	propagation delay	A to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>							
		V <sub>CC</sub> = 0.8 V	-	36.3	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.9	9.7	19.0	3.7	19.8	20.1	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	3.5	7.0	11.2	3.6	12.4	13.0	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	3.5	6.0	9.2	3.4	10.1	10.7	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	3.4	5.1	7.0	3.2	7.5	7.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	3.3	4.8	6.2	3.1	7.1	7.5	ns
<b>C<sub>L</sub> = 5 pF, 10 pF, 15 pF and 30 pF</b>									
C <sub>PD</sub>	power dissipation capacitance	f = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup>							
		V <sub>CC</sub> = 0.8 V	-	2.5	-	-	-	-	pF
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	2.7	-	-	-	-	pF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	2.8	-	-	-	-	pF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	3.0	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	3.5	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	4.0	-	-	-	pF	

[1] All typical values are measured at nominal V<sub>CC</sub>.  
 [2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.  
 [3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.



12. Waveforms

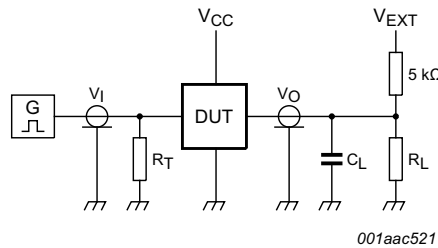


Measurement points are given in [Table 9](#).  
 Logic levels: VOL and VOH are typical output voltage levels that occur with the output load.

Fig 8. The data input (A) to output (Y) propagation delays

Table 9. Measurement points

Supply voltage	Output	Input		
VCC	VM	VM	VI	tr = tf
0.8 V to 3.6 V	0.5 × VCC	0.5 × VCC	VCC	≤ 3.0 ns



Test data is given in [Table 10](#).  
 Definitions for test circuit:  
 RL = Load resistance.  
 CL = Load capacitance including jig and probe capacitance.  
 RT = Termination resistance should be equal to the output impedance Zo of the pulse generator.  
 VEXT = External voltage for measuring switching times.

Fig 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load		VEXT		
VCC	CL	RL [1]	tPLH, tPHL	tPZH, tPHZ	tPZL, tPLZ
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × VCC

[1] For measuring enable and disable times, RL = 5 kΩ, for measuring propagation delays, setup and hold times and pulse width RL = 1 MΩ.

### 13. Transfer characteristics

**Table 11. Transfer characteristics**

Voltages are referenced to GND (ground = 0 V).

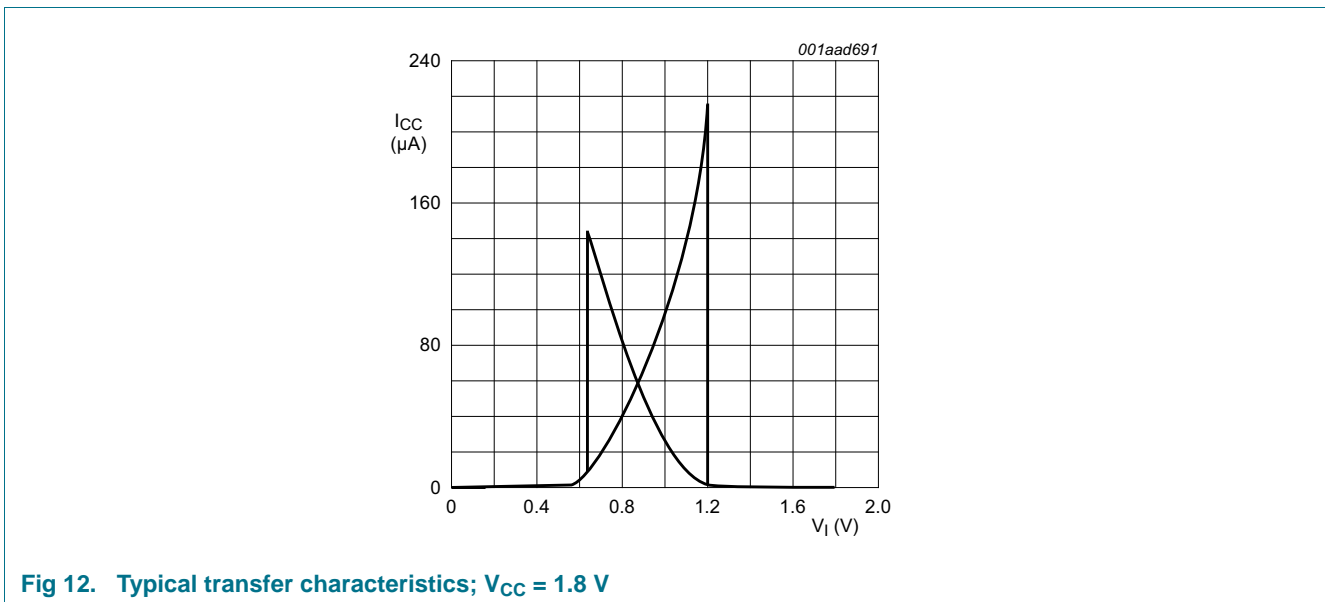
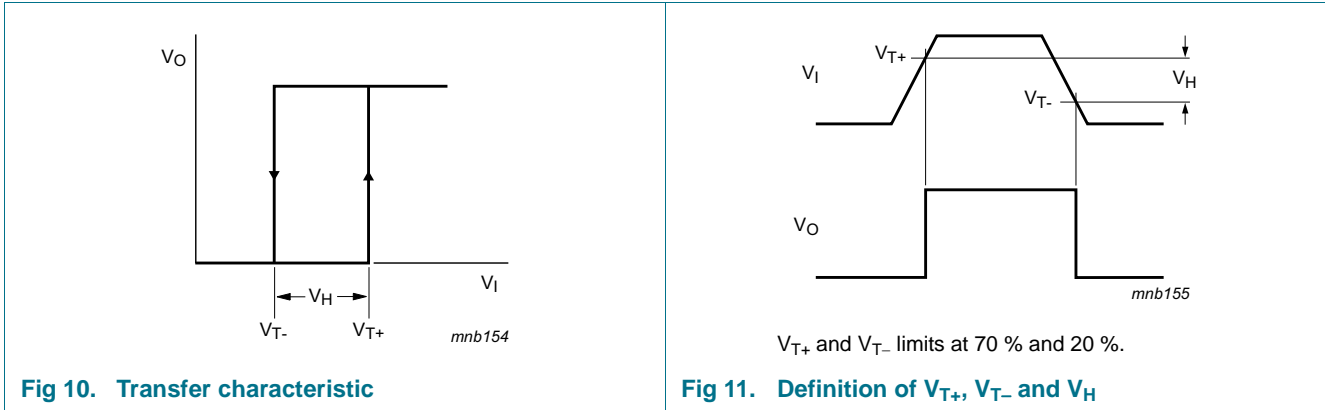
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>T<sub>amb</sub> = 25 °C</b>						
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.30	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.90	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.11	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.29	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.77	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.10	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	V
V <sub>H</sub>	hysteresis voltage	see <a href="#">Figure 10</a> , <a href="#">Figure 11</a> , <a href="#">Figure 12</a> and <a href="#">Figure 13</a>				
		V <sub>CC</sub> = 0.8 V	0.07	-	0.50	V
		V <sub>CC</sub> = 1.1 V	0.08	-	0.46	V
		V <sub>CC</sub> = 1.4 V	0.18	-	0.56	V
		V <sub>CC</sub> = 1.65 V	0.27	-	0.66	V
		V <sub>CC</sub> = 2.3 V	0.53	-	0.92	V
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.30	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.90	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.11	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.29	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.77	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.10	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	V
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.30	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.90	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.11	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.29	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.77	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.10	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	V
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.30	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.90	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.11	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.29	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.77	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.10	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	V

**Table 11. Transfer characteristics ...continued**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>H</sub>	hysteresis voltage	see <a href="#">Figure 10</a> , <a href="#">Figure 11</a> , <a href="#">Figure 12</a> and <a href="#">Figure 13</a>				
		V <sub>CC</sub> = 0.8 V	0.07	-	0.50	V
		V <sub>CC</sub> = 1.1 V	0.08	-	0.46	V
		V <sub>CC</sub> = 1.4 V	0.18	-	0.56	V
		V <sub>CC</sub> = 1.65 V	0.27	-	0.66	V
		V <sub>CC</sub> = 2.3 V	0.53	-	0.92	V
		V <sub>CC</sub> = 3.0 V	0.79	-	1.31	V
<b>T<sub>amb</sub> = -40 °C to +125 °C</b>						
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.30	-	0.62	V
		V <sub>CC</sub> = 1.1 V	0.53	-	0.92	V
		V <sub>CC</sub> = 1.4 V	0.74	-	1.13	V
		V <sub>CC</sub> = 1.65 V	0.91	-	1.31	V
		V <sub>CC</sub> = 2.3 V	1.37	-	1.80	V
		V <sub>CC</sub> = 3.0 V	1.88	-	2.32	V
V <sub>T-</sub>	negative-going threshold voltage	see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>				
		V <sub>CC</sub> = 0.8 V	0.10	-	0.60	V
		V <sub>CC</sub> = 1.1 V	0.26	-	0.65	V
		V <sub>CC</sub> = 1.4 V	0.39	-	0.75	V
		V <sub>CC</sub> = 1.65 V	0.47	-	0.84	V
		V <sub>CC</sub> = 2.3 V	0.69	-	1.04	V
		V <sub>CC</sub> = 3.0 V	0.88	-	1.24	V
V <sub>H</sub>	hysteresis voltage	see <a href="#">Figure 10</a> , <a href="#">Figure 11</a> , <a href="#">Figure 12</a> and <a href="#">Figure 13</a>				
		V <sub>CC</sub> = 0.8 V	0.07	-	0.50	V
		V <sub>CC</sub> = 1.1 V	0.08	-	0.46	V
		V <sub>CC</sub> = 1.4 V	0.18	-	0.56	V
		V <sub>CC</sub> = 1.65 V	0.27	-	0.66	V
		V <sub>CC</sub> = 2.3 V	0.53	-	0.92	V
		V <sub>CC</sub> = 3.0 V	0.79	-	1.31	V

14. Waveforms transfer characteristics



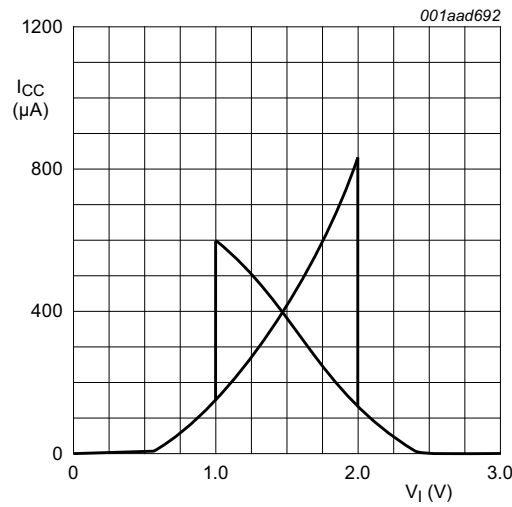


Fig 13. Typical transfer characteristics; V<sub>CC</sub> = 3.0 V

## 15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$P_{ad} = f_i \times (t_r \times I_{CC(AV)} + t_f \times I_{CC(AV)}) \times V_{CC}$  where:

$P_{ad}$  = additional power dissipation (µW);

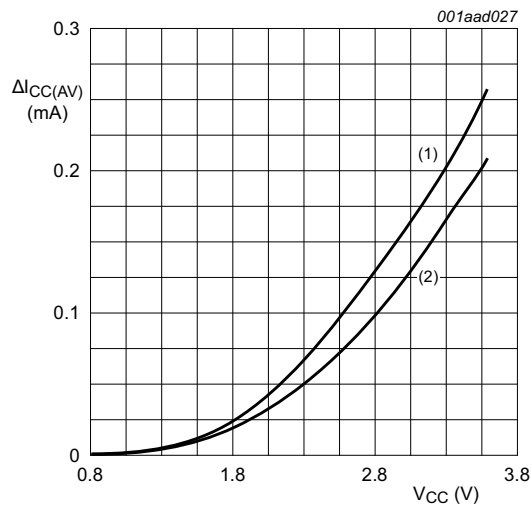
$f_i$  = input frequency (MHz);

$t_r$  = input rise time (ns); 10 % to 90 %;

$t_f$  = input fall time (ns); 90 % to 10 %;

$I_{CC(AV)}$  = average additional supply current (µA).

Average I<sub>CC</sub> differs with positive or negative input transitions, as shown in [Figure 14](#).



- (1) Positive-going edge.
- (2) Negative-going edge.

Linear change of  $V_I$  between 0.8 V and 2.0 V. All values given are typical, unless otherwise specified.

**Fig 14. Average  $I_{CC}$  as a function of  $V_{CC}$**

16. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

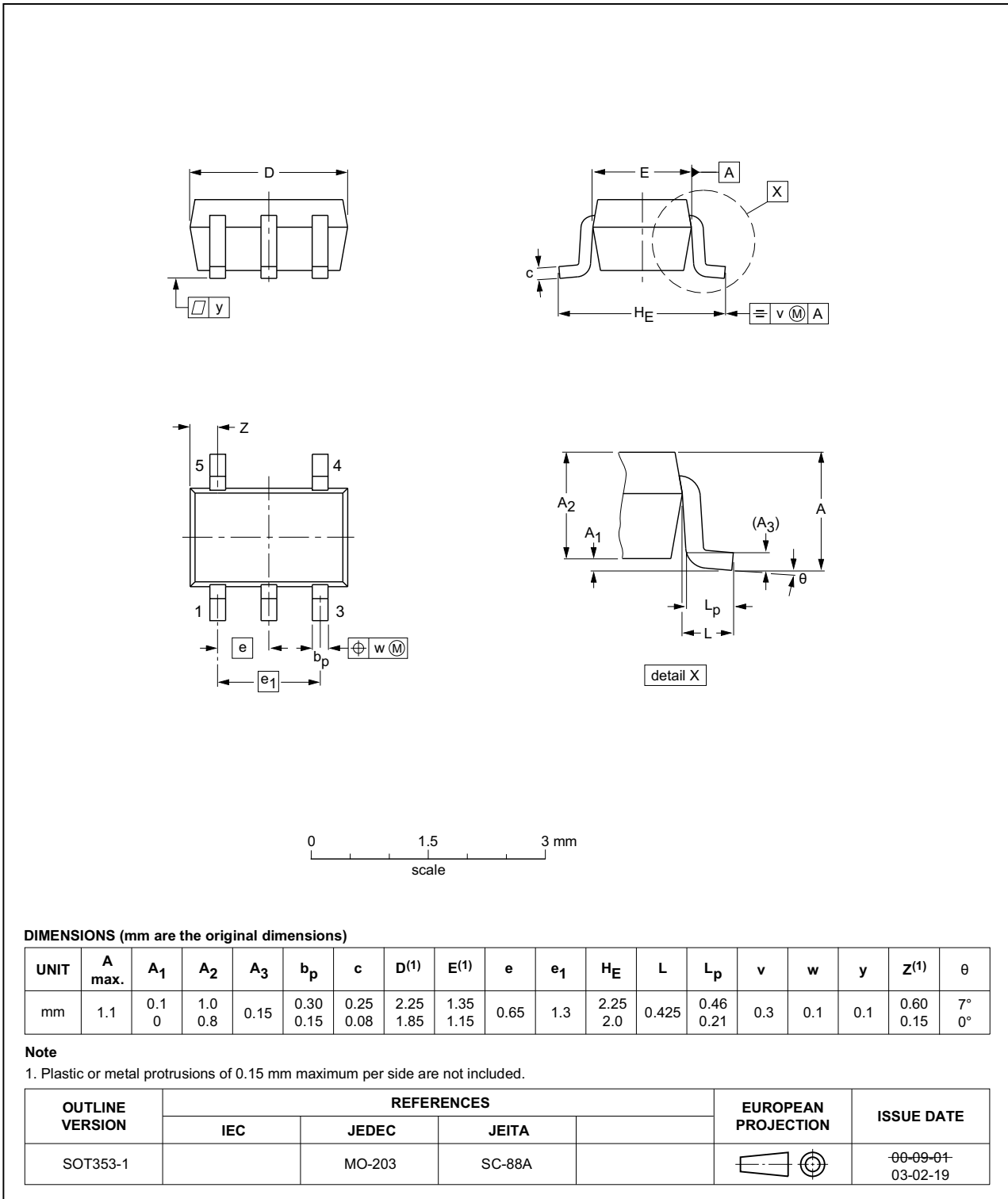


Fig 15. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

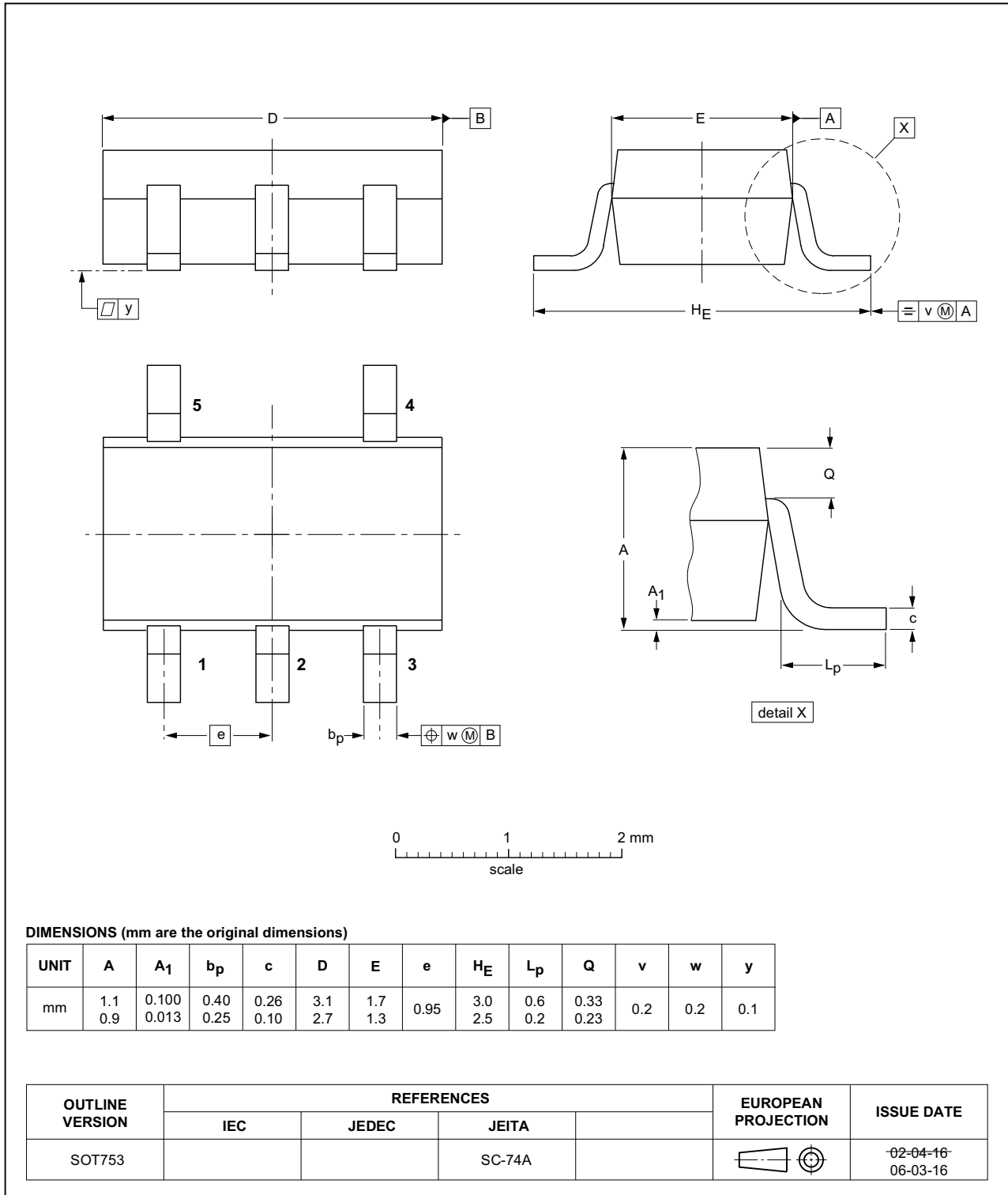


Fig 16. Package outline SOT753 (SC-74A)



XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

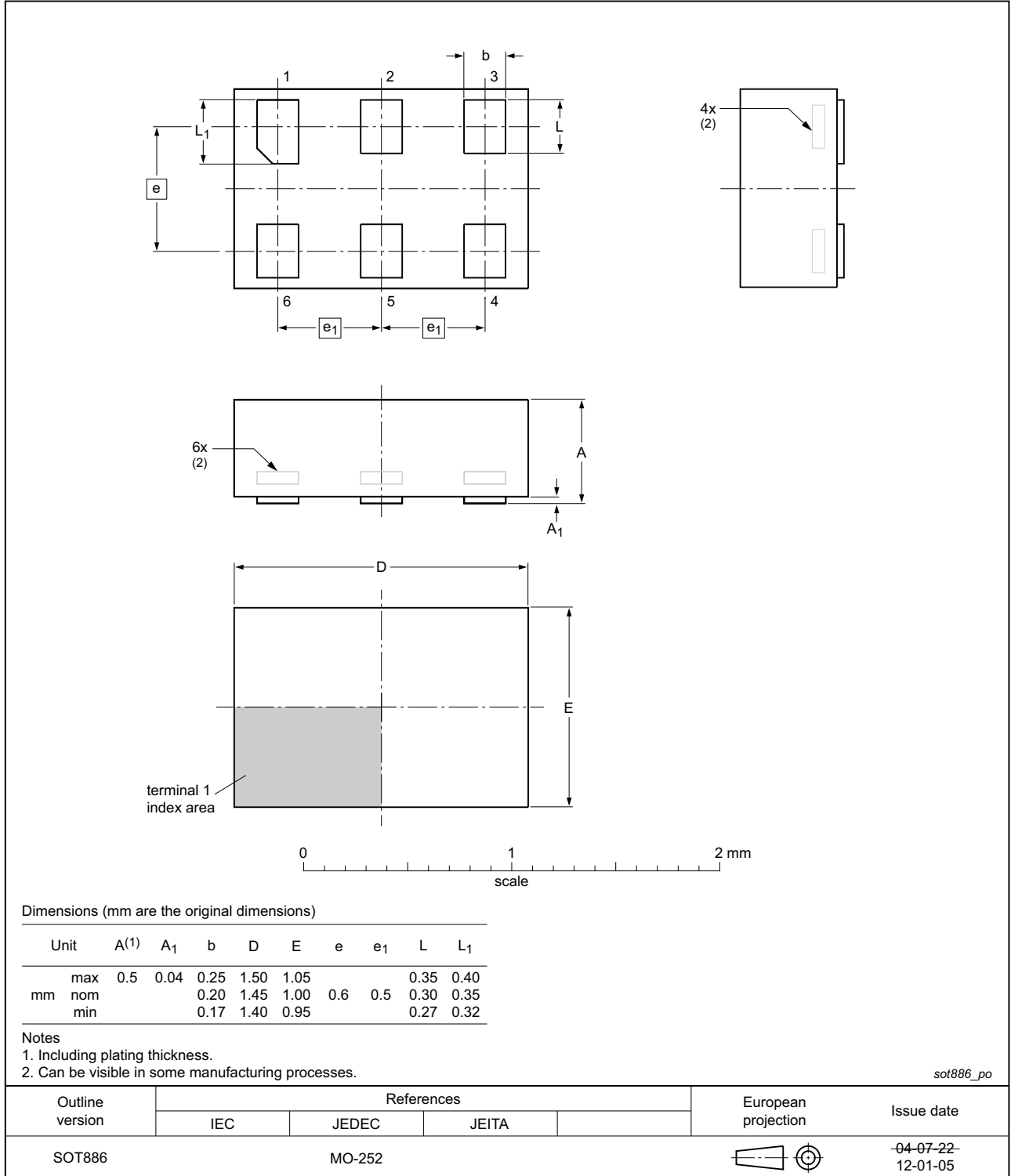


Fig 17. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

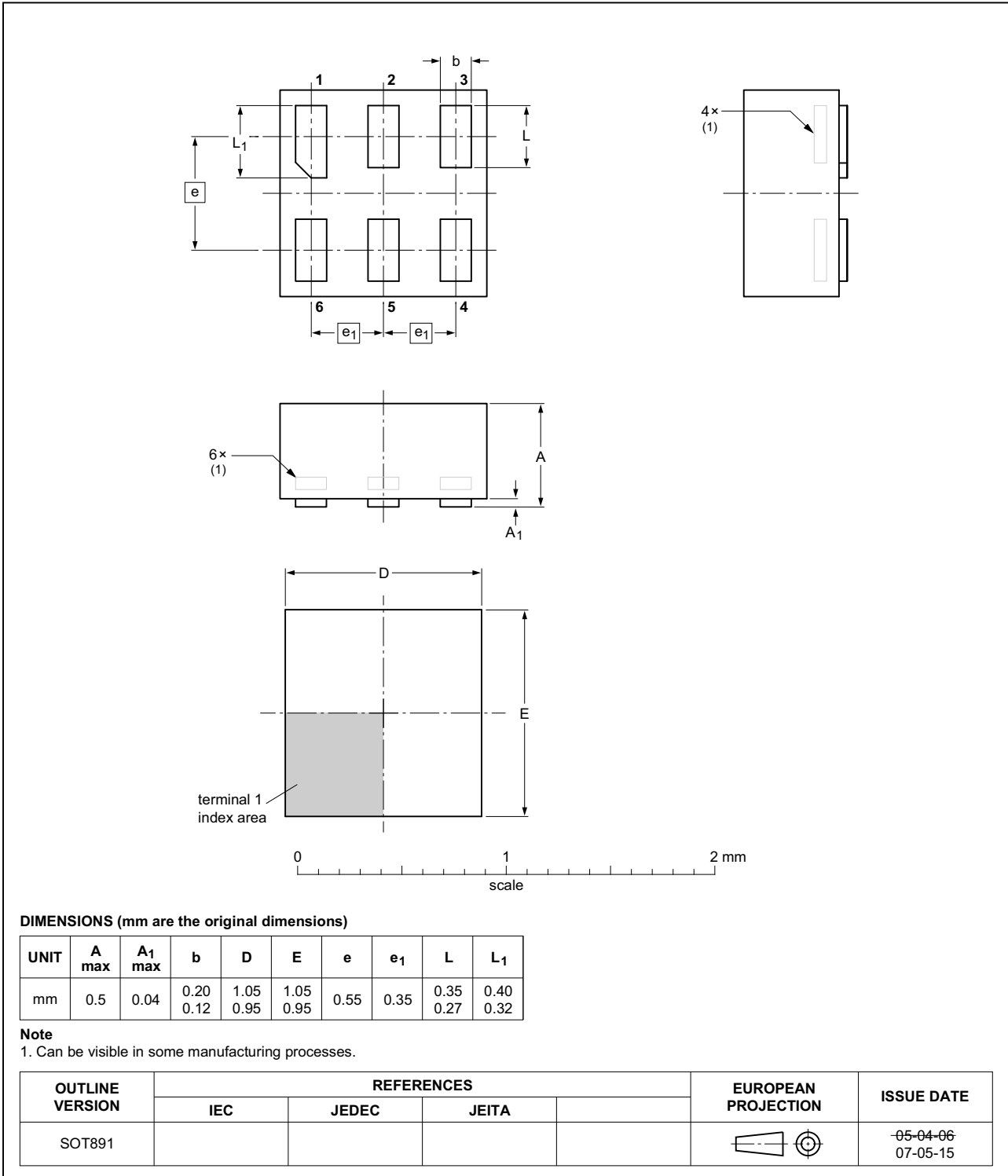


Fig 18. Package outline SOT891 (XSON6)

**XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115

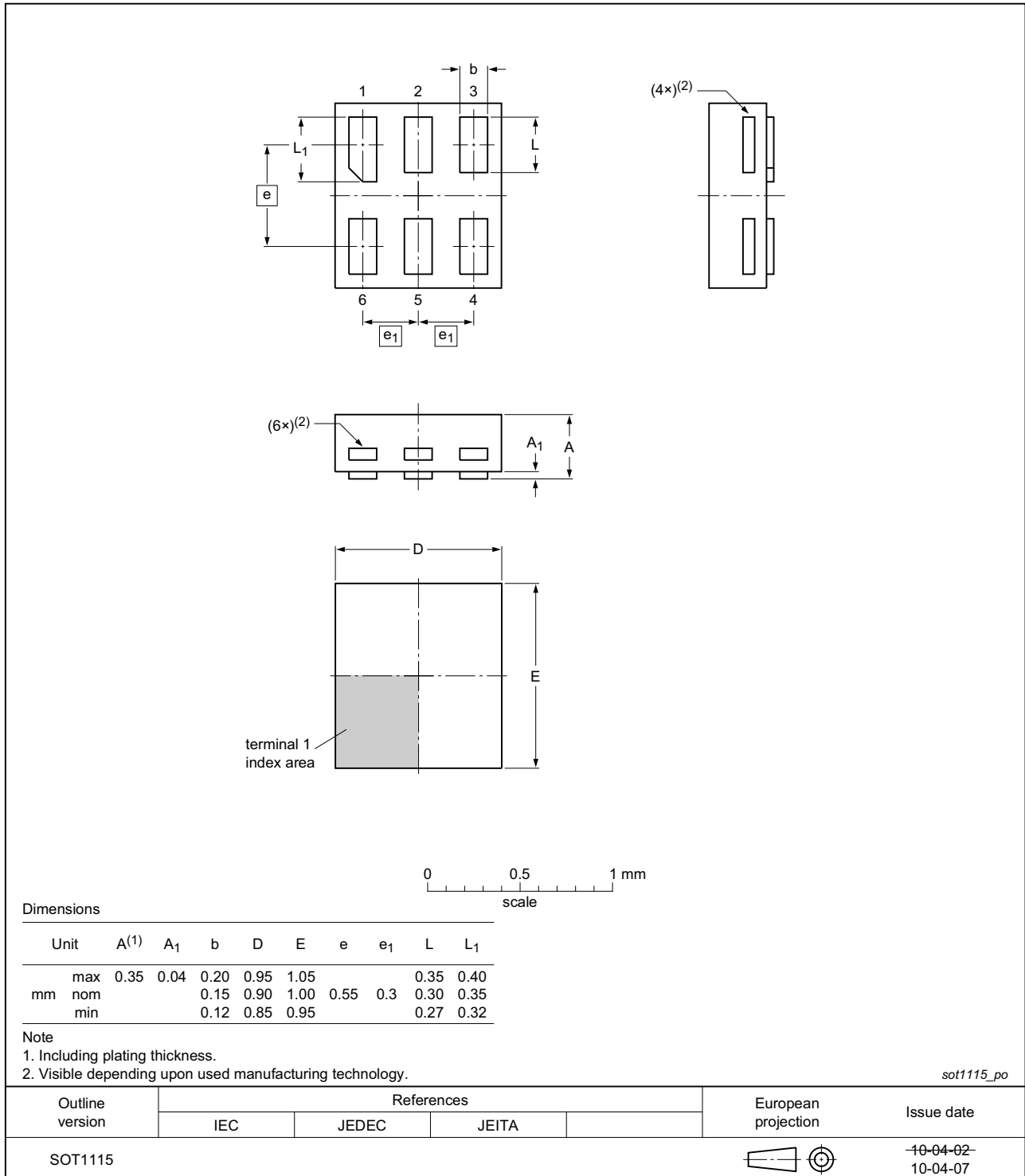


Fig 19. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;**  
**6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

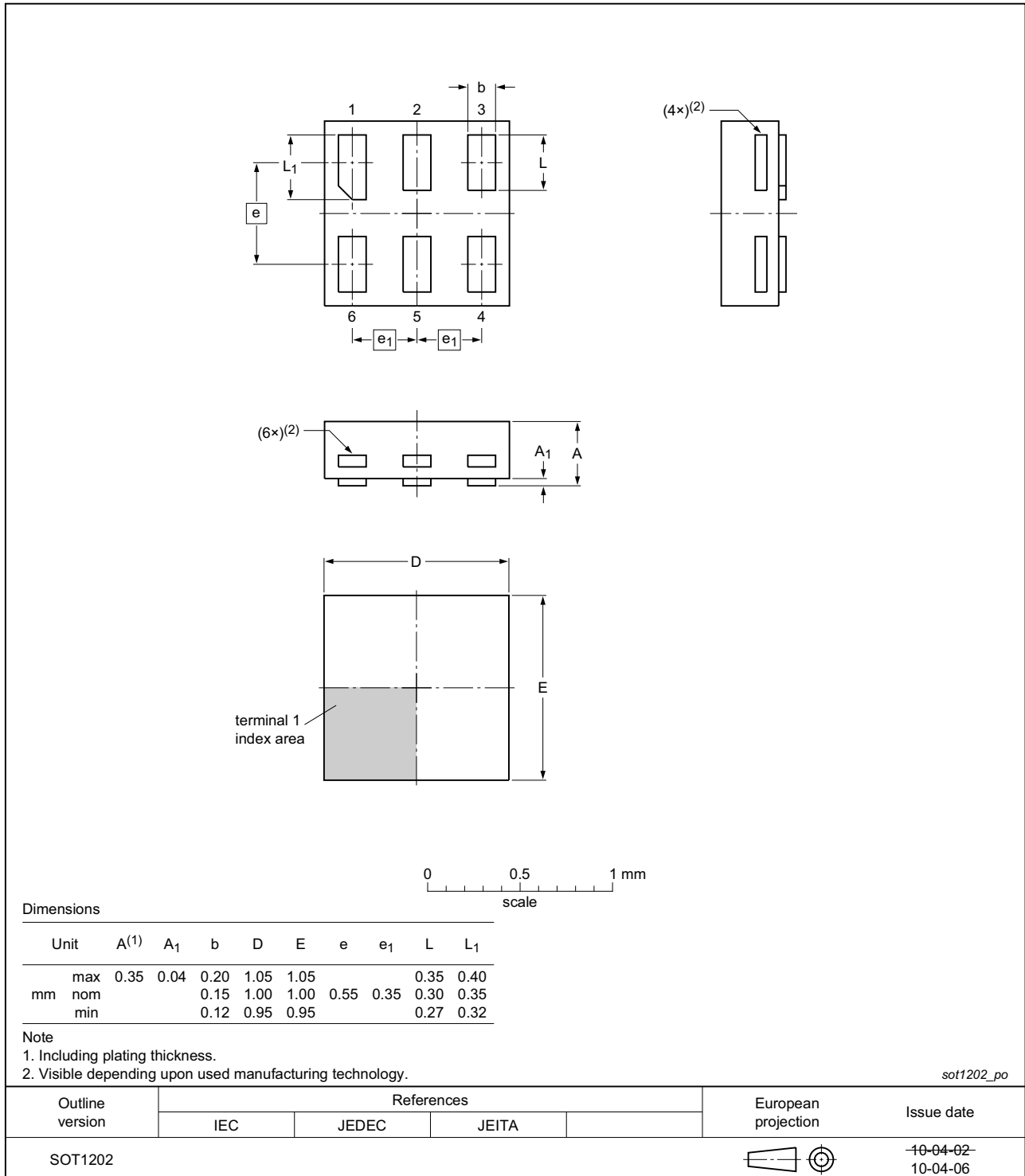


Fig 20. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

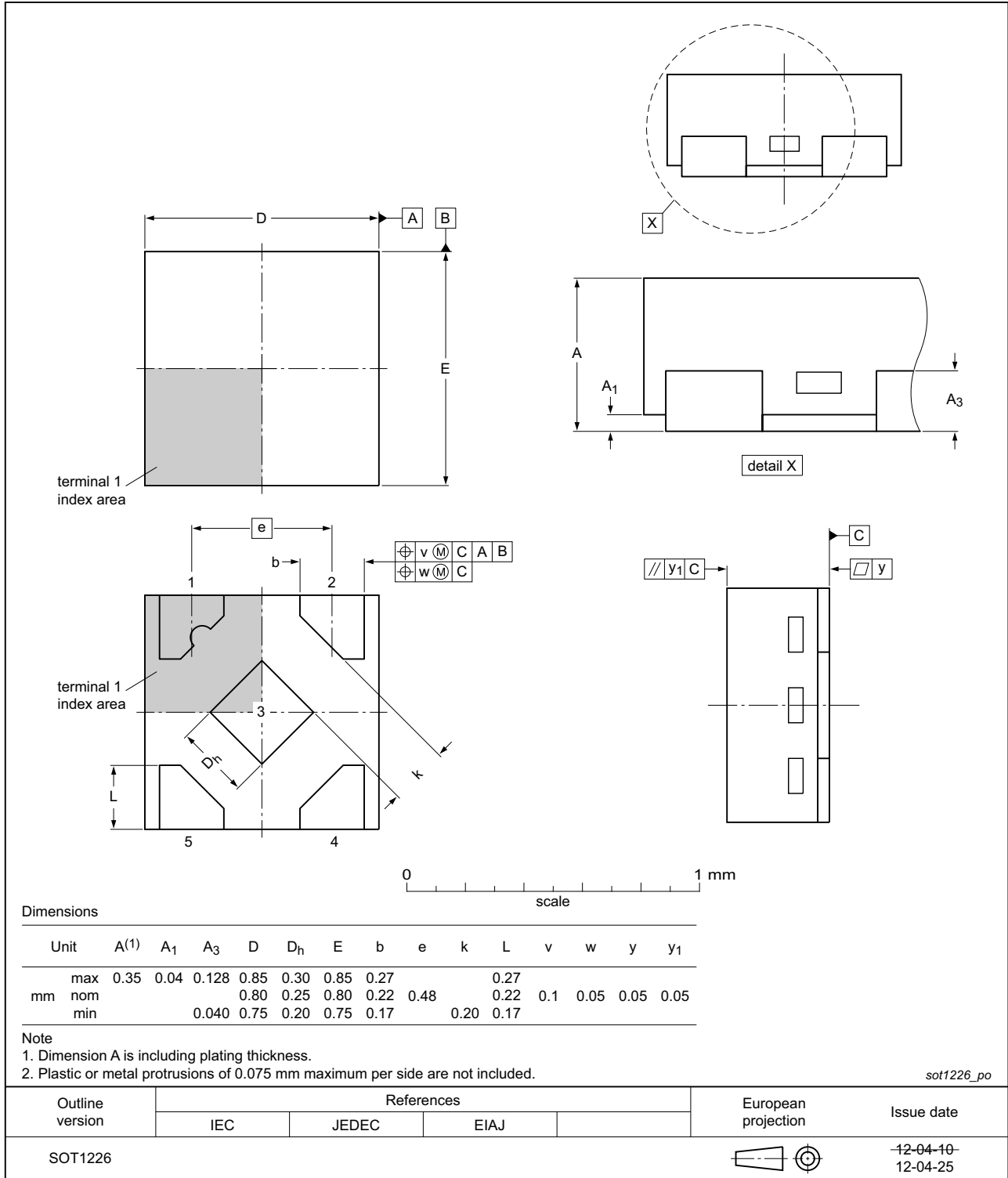


Fig 21. Package outline SOT1226 (X2SON5)

## 17. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 18. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G17 v.9	20161104	Product data sheet	-	74AUP1G17 v.8
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74AUP1G17GV (SOT753)</li> </ul>			
74AUP1G17 v.8	20150115	Product data sheet	-	74AUP1G17 v.7
Modifications:	<ul style="list-style-type: none"> <li>Marking code <a href="#">Table 2</a>: typo corrected in type number 74AUP1G17GX.</li> </ul>			
74AUP1G17 v.7	20120716	Product data sheet	-	74AUP1G17 v.6
Modifications:	<ul style="list-style-type: none"> <li>Package outline drawing of SOT1226 (<a href="#">Figure 21</a>) modified.</li> </ul>			
74AUP1G17 v.6	20120412	Product data sheet	-	74AUP1G17 v.5
Modifications:	<ul style="list-style-type: none"> <li>Added type number 74AUP1G17GX (SOT1226)</li> <li>Package outline drawing of SOT886 (<a href="#">Figure 17</a>) modified.</li> </ul>			
74AUP1G17 v.5	20111124	Product data sheet	-	74AUP1G17 v.4
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74AUP1G17 v.4	20100715	Product data sheet	-	74AUP1G17 v.3
74AUP1G17 v.3	20090710	Product data sheet	-	74AUP1G17 v.2
74AUP1G17 v.2	20060727	Product data sheet	-	74AUP1G17 v.1
74AUP1G17 v.1	20050726	Product data sheet	-	-

## 19. Legal information

### 19.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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